

Enhancement Mode N-Channel Power MOSFET

 $TO-252/NMOS/20V/\pm12V/0.75V/50A/6.0m\Omega$

Re0.5





20V, 6.0mΩ, 50A, Single N-Channel

1.Features

- ◆ 20V MOSFET technology
- ◆ Low on-state resistance
- Fast switching
- ♦ Vgs±12V

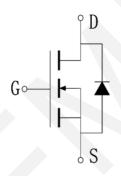
		4.
2.Ap	plica	ations

- Power Switching Application
- Load Switching



Pin Description

V _{DS}	R _{DS(on)} Typ.	I _D Max.	
20V	6.0mΩ @ 4.5V	50A	
	9.7mΩ @ 2.5V	50A	



Schematic Diagram

3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP2050KA	WP2050KA	TO-252	2,500	25,000

4Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	$V_{ extsf{DSS}}$	20	V
Gate to Source Voltage	V_{GSS}	±12	V
Drain Current (DC)	I _D	50	А
Drain Current (Pulse), PW≤300μs	I _{DP}	200	А
Total Dissipation	P_{D}	30	W
Avalanche Energy, Single Pulsed	E _{AS}	81	mJ
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



5. Thermal Resistance Ratings (Note 2)

Parameter	Symbol	Value	Unit
Junction to Ambient	$R_{ hetaJA}$	32	°C/W
Junction to case	R _{eJC}	3.4	°C/W

Note 2: When mounted on 1 inch square copper board t ≤ 10sec The value in any given application depends on the user's specific board design.

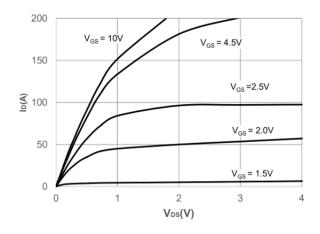
6.Electrical Characteristics at Ta=25°C (Note 3)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V _{(BR)DSS}	$I_D = 250 \mu A, V_{GS} = 0 V$	20	-	1	V
Zero-Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 18V, V_{GS} = 0V$	ı	-	1	μA
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 12V$, $V_{DS} = 0V$	ľ	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{DS}=250\mu A$	0.5	0.75	1.3	V
Static Drain to Source On-State	Б	$I_D = 25A, V_{GS} = 4.5V$	-	6.0	7.8	mΩ
Resistance	R _{DS(on)}	I _D = 10A, V _{GS} =2.5V	-	9.7	15.0	mΩ
Input Capacitance	C _{iss}	V _{GS} =0V,	-	1651	-	pF
Output Capacitance	C _{oss}	V _{DS} =10V,	-	278	-	pF
Reverse Transfer Capacitance	C_{rss}	Frequency=1.0MHz	ı	252	-	pF
Turn-ON Delay Time	t _{d(on)}		-	12	-	ns
Rise Time	t _r	$V_{DD} = 10V, I_D = 20A,$	-	33	-	ns
Turn-OFF Delay Time	$t_{d(off)}$	$V_{GS} = 4.5V,$ $R_G = 3\Omega,$	-	48	-	ns
Fall Time	t _f	,	-	95	-	ns
	Q_g	$V_{DS} = 10V,$ $V_{GS} = 4.5V,$ $I_{D} = 20A$	-	23	-	nC
Total Gate Charge	Q _{gs}		-	4	-	nC
	Q_{gd}		-	7	-	nC
Diode Forward Voltage	V _{FSD}	I _S = 25A, V _{GS} = 0V	0.4	0.85	1.2	V

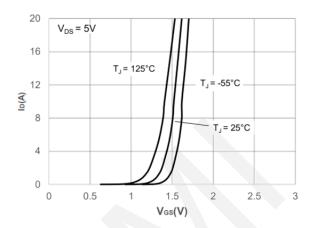
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



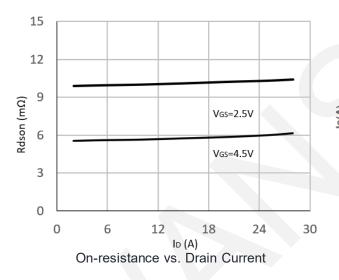
7. Typical electrical and thermal characteristics

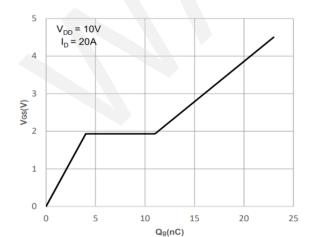




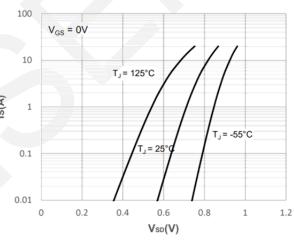


Typical Transfer Characteristics

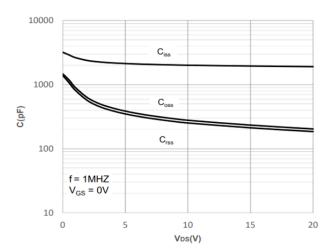




Gate Charge Characteristics

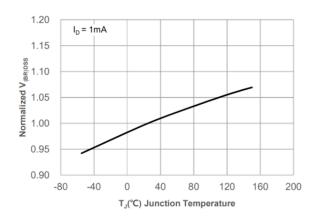


Body Diode Characteristics



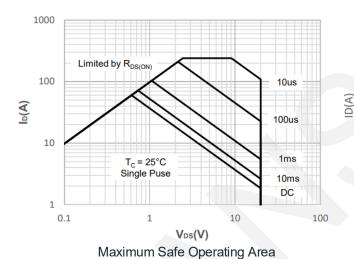
Capacitance Characteristics

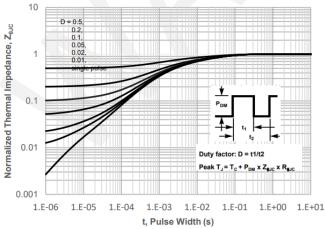




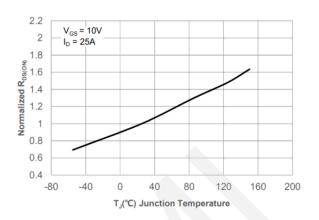
Normalized Breakdown Voltage vs.

Junction Temperature



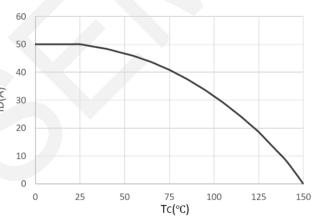


Normalized Maximum Transient Thermal Impedance

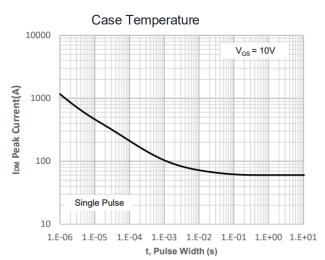


Normalized on Resistance vs.

Junction Temperature



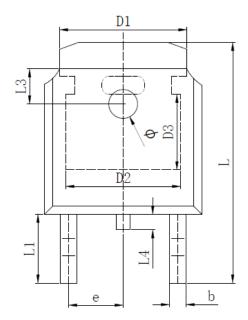
Maximum Continuous Drain Current vs.

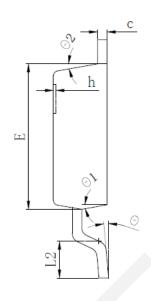


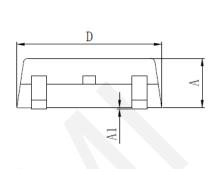
Peak Current Capacity



8.Package Dimensions







SYMBOL	MILLIMETER			
SIMDOL	MIN	Тур.	MAX	
A	2. 200	2. 300	2. 400	
A1	0.000		0. 127	
b	0.640	0.690	0. 740	
c(电镀后)	0. 460	0. 520	0. 580	
D	6. 500	6. 600	6. 700	
D1	5. 334 REF			
D2		4.826 REF		
D3		3.166 REF		
E	6. 000	6. 100	6. 200	
e	2.286 TYP			
h	0.000	0.100	0. 200	
L	9. 900	10. 100	10. 300	
L1	2.888 REF			
L2	1. 400	1.550	1. 700	
L3	1.600 REF			
L4	0.600	0.800	1.000	
ф	1. 100	1. 200	1. 300	
θ	0°		8°	
θ1	9° TYP			
θ2	9° TYP			



9. Important Notice

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